



## N-Channel 80 V (D-S) MOSFET

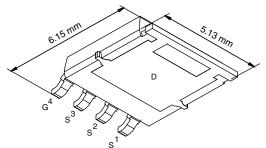
PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ ) (Max.)	I <sub>D</sub> (A) <sup>a, g</sup>	Q <sub>g</sub> (Typ.)			
	0.0062 at V <sub>GS</sub> = 10 V					
80	0.0065 at V <sub>GS</sub> = 7.5 V	60	24 nC			
	0.0095 at V <sub>GS</sub> = 4.5 V					

#### **FEATURES**

- TrenchFET® Power MOSFET
- 100 % R<sub>a</sub> and UIS Tested
- Capable of Operating with 5 V Gate Drive
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



#### PowerPAK® SO-8L Single

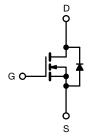


#### Ordering Information:

SiJ482DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

#### **APPLICATIONS**

- DC/DC Primary Side Switch
- Synchronous Rectification
- High Current Switching



N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	$V_{DS}$	80	V		
Gate-Source Voltage	$V_{GS}$	± 20			
	T <sub>C</sub> = 25 °C		60 <sup>g</sup>		
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I_	60 <sup>g</sup>		
Continuous Brain Guirent (1) = 130 C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	21.1 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		16.9 <sup>b, c</sup>	A	
Pulsed Drain Current (t = 300 μs)		I <sub>DM</sub>	100	_ ^	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	l-	60 <sup>g</sup>		
Continuous Source-Diam Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	4.5 <sup>b, c</sup>		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	30		
Single Pulse Avalanche Energy	L=0.111111	E <sub>AS</sub>	45	mJ	
	T <sub>C</sub> = 25 °C		69.4		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	P <sub>D</sub>	44.4	w	
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	' b	5 <sup>b, c</sup>	• • • • • • • • • • • • • • • • • • • •	
	T <sub>A</sub> = 70 °C		3.2 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		
Soldering Recommendations (Peak Temperatur		260	°C		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, f</sup>	t ≤ 10 s	R <sub>thJA</sub>	20	25	°C/W
Maximum Junction-to-Case (Drain)	Steady State	$R_{thJC}$	1.3	1.8	J/VV

- a. Based on  $T_C$  = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions is 65 °C/W.
- g. Package limited.

## SiJ482DP

## Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				1			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	80			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			36			
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 5.7		mV/°(	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.5		2.7	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
	_	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5 V, V <sub>GS</sub> = 10 V	30			Α	
	. ,	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0051	0.0062		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 7.5 V, I <sub>D</sub> = 15 A		0.0054	0.0065	Ω	
	- (1)	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A		0.0068	0.0095		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 20 A		68		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			2425			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1180		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	50 - 7 do - 7		100		ρ.	
Therefore Transfer Capacitanies	- 133	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		47	71		
Total Gate Charge	$Q_{g}$	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 7.5 V, I <sub>D</sub> = 10 A		36.5	55		
3.	9	23 - 7 do - 7 D -		24	36		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 40 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		6.6		nC	
Gate-Drain Charge	Q <sub>gd</sub>	20 / GO / D		10.2			
Output Charge	Q <sub>oss</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V		69	105		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	1.1	2.2	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			14	28		
Rise Time	t <sub>r</sub>	$V_{DD} = 40 \text{ V}, R_{I} = 4 \Omega$		11	22		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_a = 1 \Omega$		36	72		
Fall Time	t <sub>f</sub>	3		9	18		
Turn-On Delay Time	t <sub>d(on)</sub>			16	32	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 40 \text{ V}, R_{I} = 4 \Omega$		13	26		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 7.5 \text{ V}, R_g = 1 \Omega$		35	70	1	
Fall Time	t <sub>f</sub>	, and the second		11	22		
Drain-Source Body Diode Characteristic				<u> </u>			
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			60		
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				100	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 4 A		0.73	1.1	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			46	90	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			44	86	nC	
Reverse Recovery Fall Time	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$						
Reverse Recovery Rise Time	t <sub>b</sub>			25		ns	

#### Notes:

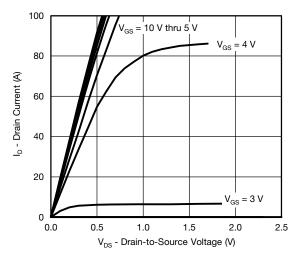
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

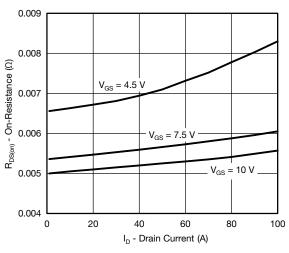
b. Guaranteed by design, not subject to production testing.



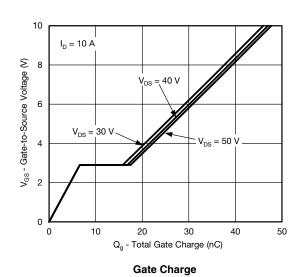
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### **Output Characteristics**



#### On-Resistance vs. Drain Current and Gate Voltage



10

8

(x)

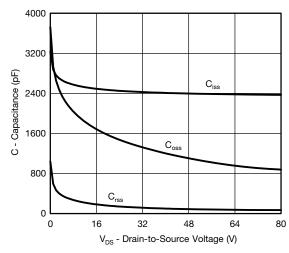
T<sub>C</sub> = 25 °C

T<sub>C</sub> = 125 °C

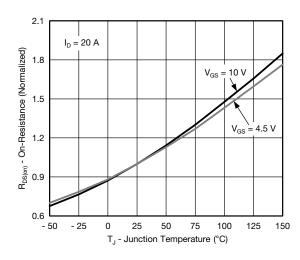
T<sub>C</sub> = -55 °C

V<sub>GS</sub> - Gate-to-Source Voltage (V)

**Transfer Characteristics** 



#### Capacitance

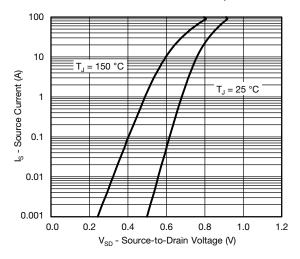


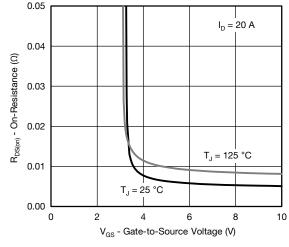
On-Resistance vs. Junction Temperature

## SiJ482DP

## Vishay Siliconix

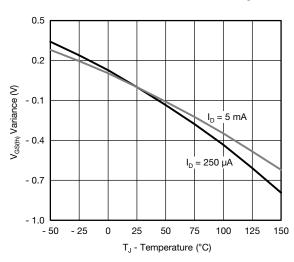
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

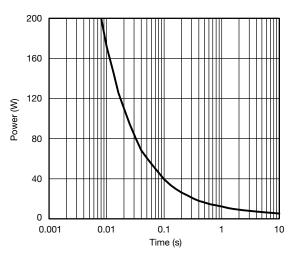




#### Source-Drain Diode Forward Voltage

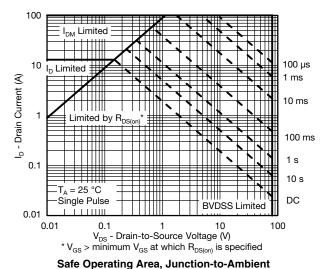






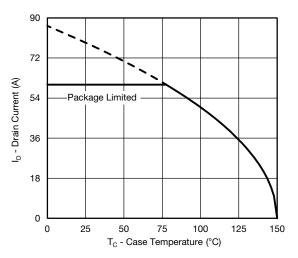
**Threshold Voltage** 

Single Pulse Power, Junction-to-Ambient

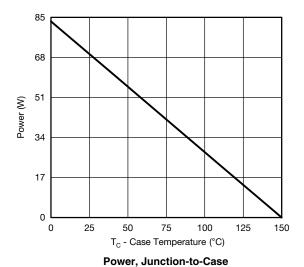


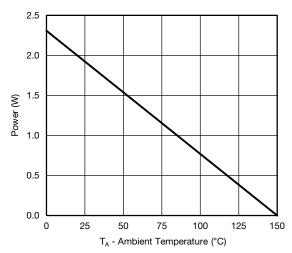


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### **Current Derating\***





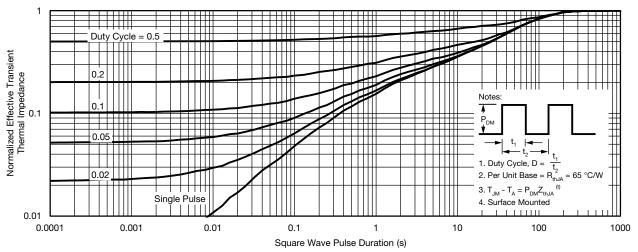
Power, Junction-to-Ambient

<sup>\*</sup> The power dissipation PD is based on TJ(max) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

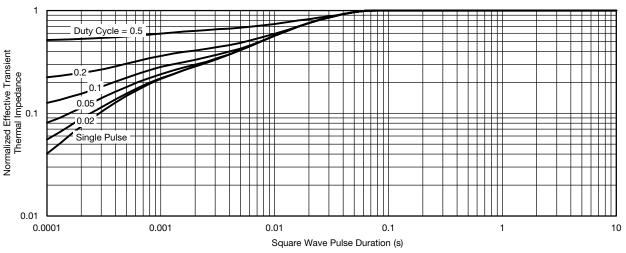
## SiJ482DP

## Vishay Siliconix

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

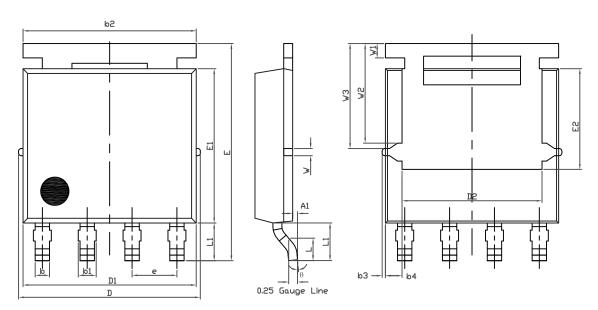


Normalized Thermal Transient Impedance, Junction-to-Case

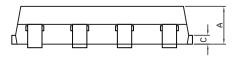
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppq?63728

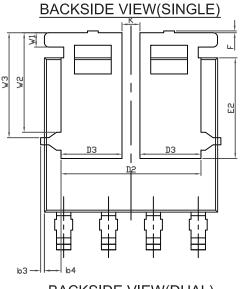


# PowerPAK® SO-8L Case Outline for Non-Al Parts



## **TOPSIDE VIEW**





BACKSIDE VIEW(DUAL)



www.vishay.com Vishay Siliconix

DIM.	MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094	•		0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	3.18	3.28	3.38	0.125	0.129	0.133	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K	0.51			0.020			
W	0.23			0.009			
W1	0.41			0.016			
W2	2.82			0.111			
W3	2.96			0.117			
q	0°	-	10°	0°	-	10°	

ECN: C15-1122-Rev. C, 07-Sep-15

DWG: 5976

#### Note

· Millimeters will gover



#### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



## **Legal Disclaimer Notice**

Vishay

## **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

## **Material Category Policy**

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000

## **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Vishay manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 JANTX2N5237 2N7000 FCA20N60\_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D

TPCC8103,L1Q(CM MIC4420CM-TR VN1206L 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C

IPS70R2K0CEAKMA1 BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI

DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384

NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956

NTE2911 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B